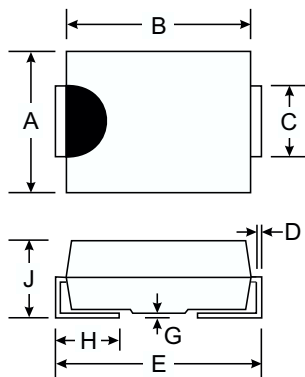


Features

- Schottky Barrier Chip
- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 50A Peak
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- High Temperature Soldering: 260°C/10 Second at Terminal
- Plastic Material - UL Flammability Classification 94V-0



Dim	SMA		SMB	
	Min	Max	Min	Max
A	2.29	2.92	3.30	3.94
B	4.00	4.60	4.06	4.57
C	1.27	1.63	1.96	2.21
D	0.15	0.31	0.15	0.31
E	4.80	5.59	5.00	5.59
G	0.10	0.20	0.10	0.20
H	0.76	1.52	0.76	1.52
J	2.01	2.62	2.00	2.62
All Dimensions in mm				

Mechanical Data

- Case: Molded Plastic
- Terminals: Solder Plated Terminal - Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- Approx. Weight: SMA 0.064 grams
SMB 0.093 grams
- Mounting Position: Any
- Marking: Type Number

No Suffix Designates SMB Package
 "A" Suffix Designates SMA Package

Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

Characteristic	Symbol	B220/A	B230/A	B240/A	B250/A	B260/A	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	20	30	40	50	60	V
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	35	42	V
Average Rectified Output Current @ $T_T = 100^{\circ}C$	I_O	2.0					A
Non-Repetitive Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50					A
Forward Voltage @ $I_F = 2.0A$	V_{FM}	0.50			0.70		V
Peak Reverse Current @ $T_A = 25^{\circ}C$ at Rated DC Blocking Voltage @ $T_A = 100^{\circ}C$	I_{RM}	0.5 20					mA
Typical Junction Capacitance (Note 2)	C_j	200					pF
Typical Thermal Resistance, Junction to Terminal	$R_{\theta JT}$	20					K/W
Typical Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	25					K/W
Operating and Storage Temperature Range	T_j, T_{STG}	-65 to +150					$^{\circ}C$

Notes: 1. Thermal Resistance: Junction to terminal, unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pad as heat sink.
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

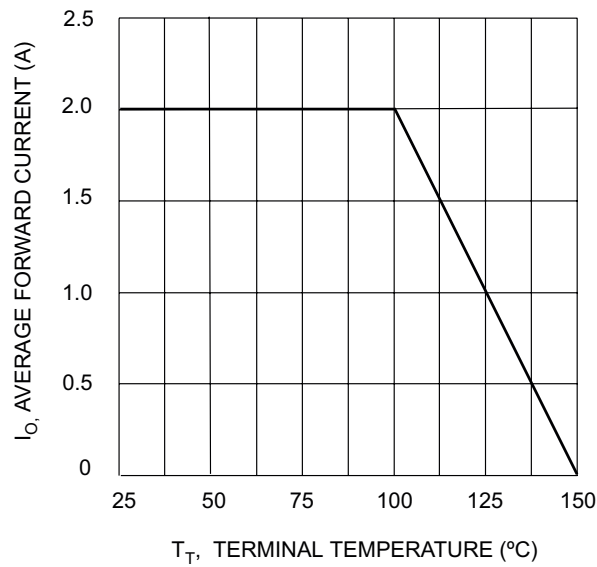


Fig. 1 Forward Current Derating Curve

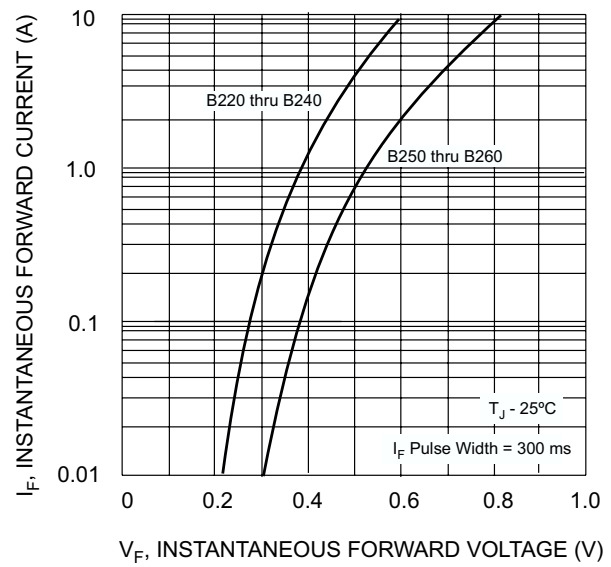


Fig. 2 Typical Forward Characteristics

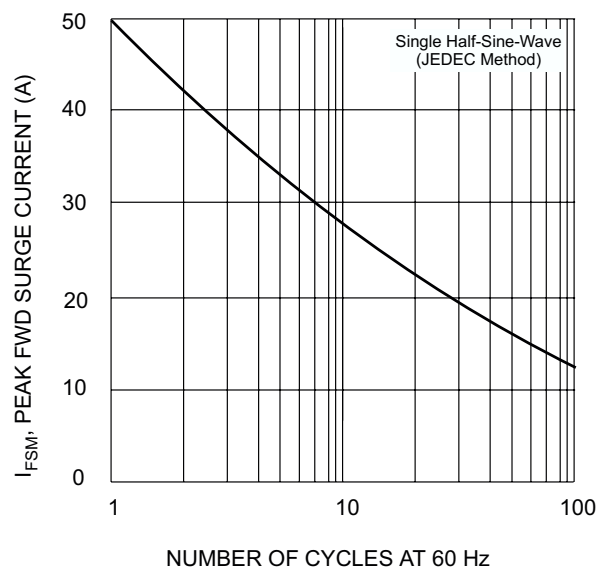


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

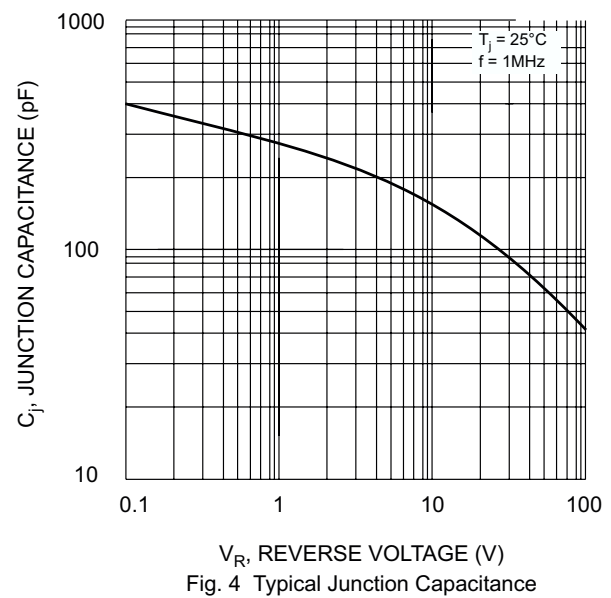


Fig. 4 Typical Junction Capacitance

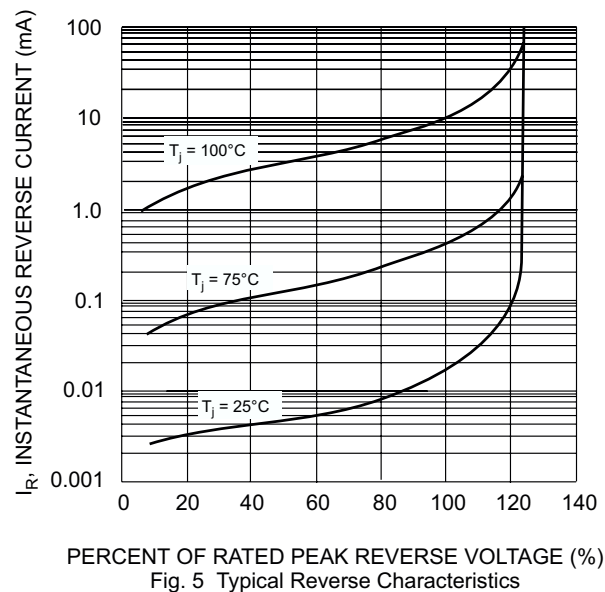


Fig. 5 Typical Reverse Characteristics